



Click [here](#) for the 3D model.

| Dimensions |                     |
|------------|---------------------|
| Chip Size  | 0402                |
| L          | 1mm +/-0.05mm       |
| W          | 0.5mm +/-0.05mm     |
| T          | 0.5mm +/-0.05mm     |
| B          | 0.25mm +0.05/-0.1mm |

  

| Packaging Specifications |                          |
|--------------------------|--------------------------|
| Packaging                | T&R, 180mm, Plastic Tape |
| Packaging Quantity       | 10000                    |

| General Information |  |
|---------------------|--|
| Series              | CBR-SMD RF COG                                 |
| Style               | SMD Chip                                       |
| Description         | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features            | Ultra High Q, Low ESR, Class I                 |
| RoHS                | Yes  |
| Termination         | Tin  |
| Marking             | No   |
| AEC-Q200            | No   |
| Component Weight    | 1.4 mg   |
| Notes               | Solder Wave or Solder Reflow.                  |
| Shelf Life          | 78 Weeks                                       |
| MSL                 | 1  |

| Specifications   |                           |
|--|---------------------------|
| Capacitance  | 6 pF                      |
| Capacitance Tolerance  | +/-0.25 pF                |
| Voltage DC   | 250 VDC                   |
| Dielectric Withstanding Voltage                                    | 625 VDC                   |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz<br>1.0Vrms |
| Dissipation Factor   | 0.2% 1MHz<br>1.0Vrms      |
| Aging Rate   | 0% Loss/Decade<br>Hour    |
| Insulation Resistance  | 10 GOhms                  |
| Quality Factor   | 520                       |